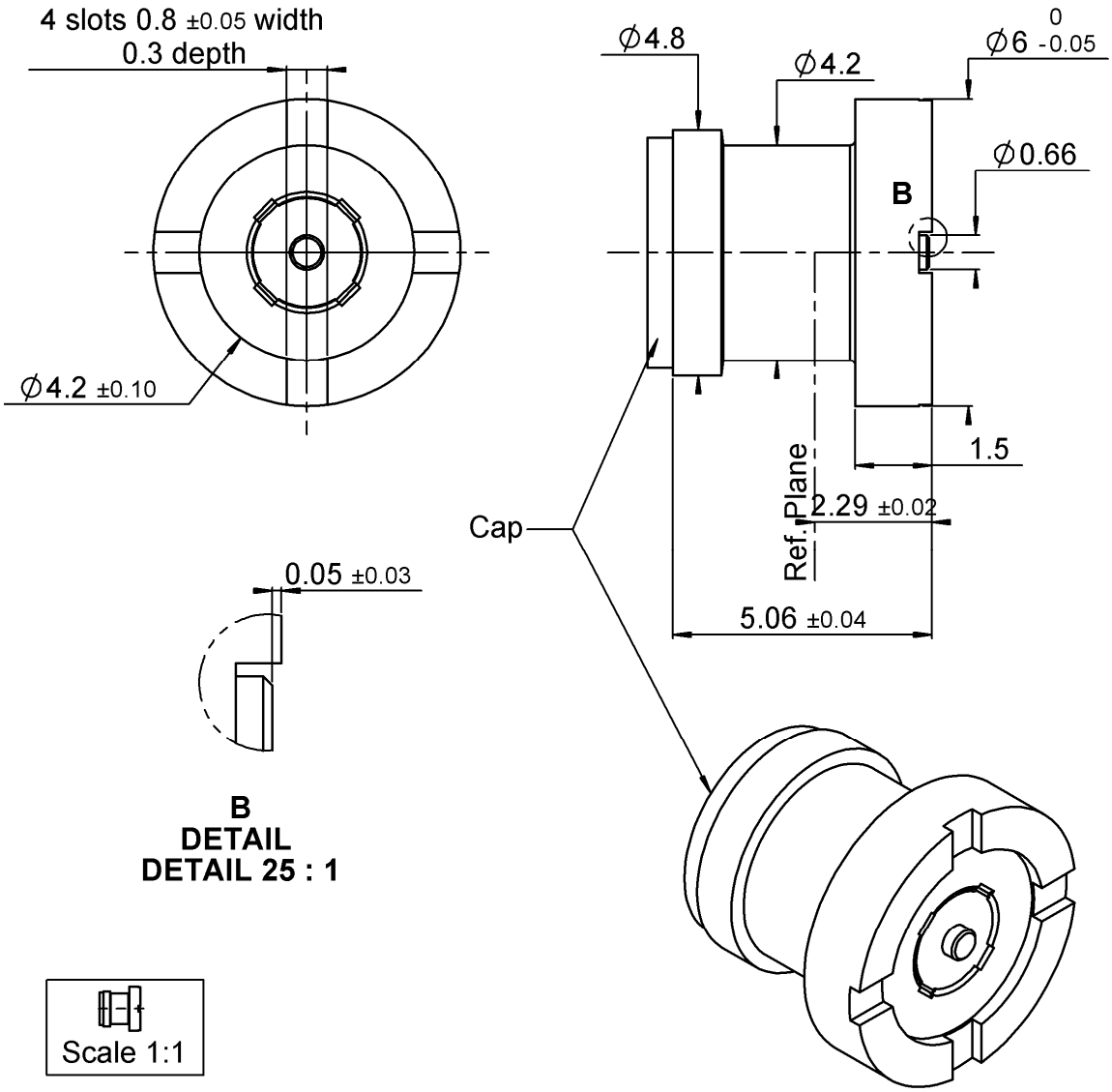
MALE STRAIGHT RECEPTACLE FOR PCB

LIMITED DETENT REEL 100

R222.L00.010

Series : **SMP LOCK**



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
BODY	**BRASS**	**N2PGR**
CENTER CONTACT	**BERYLLIUM COPPER**	**N2PGR**
OUTER CONTACT	-	-
INSULATOR	**PTFE**	
GASKET	-	
OTHERS PARTS	**PTFE**	-
-	-	-
-	-	-

Issue : 1312 A

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PACKAGING

Standard	Unit	Other
100	**W**	**Contact us**

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance			**50**	Ω
Frequency			**0-18**	GHz
VSWR	**1.05***	+	**0,0170**	x F(GHz) Maxi
Insertion loss			**0.12**	√F(GHz) dB Maxi
RF leakage		- (	**90***	- F(GHz)) dB Maxi
Voltage rating			**335**	Veff Maxi
Dielectric withstanding voltage			**500**	Veff mini
Insulation resistance			**5000**	MΩ mini

ENVIRONMENTAL

Operating temperature	**-65/+165**	° C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

OTHER CHARACTERISTICS

Assembly instruction

Others :
*Coaxial Transmission Line Only

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	**6.7**	N mini
Axial force – Opposite end	**6.7**	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating	**NA**	N.cm
Panel nut	**NA**	N.cm
Mating life	**500**	Cycles mini
Weight	**0,5700**	g

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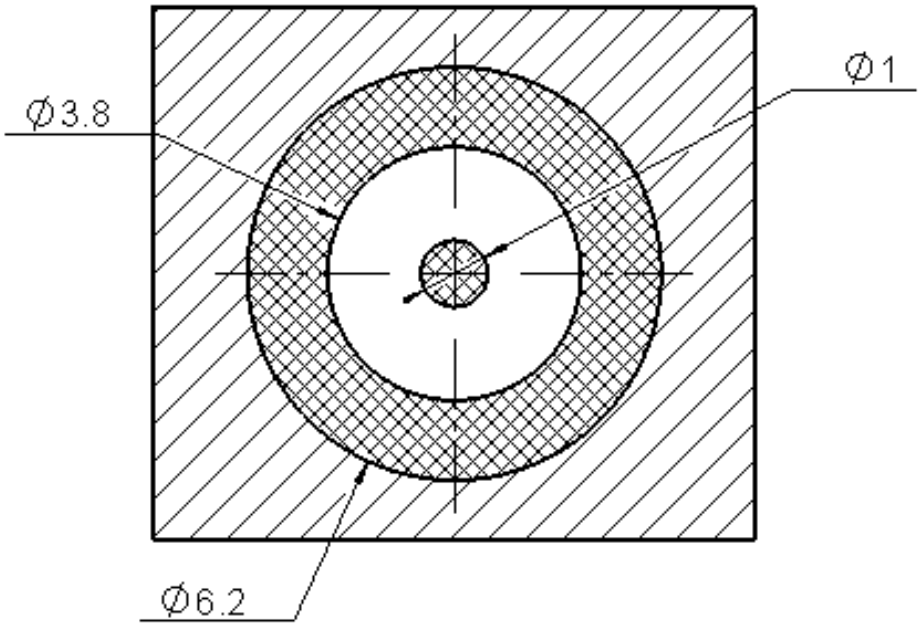
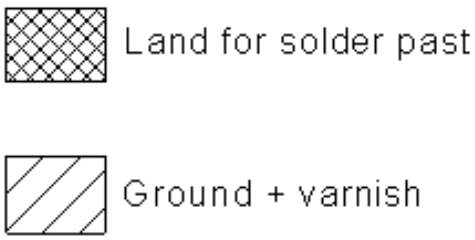
STANDARD PAD (RADIALL RECOMMANDATION)





-The landing pad for center contact should be linked to the stripline using a filled via.
-Upper and lower ground planes should be linked using vias.

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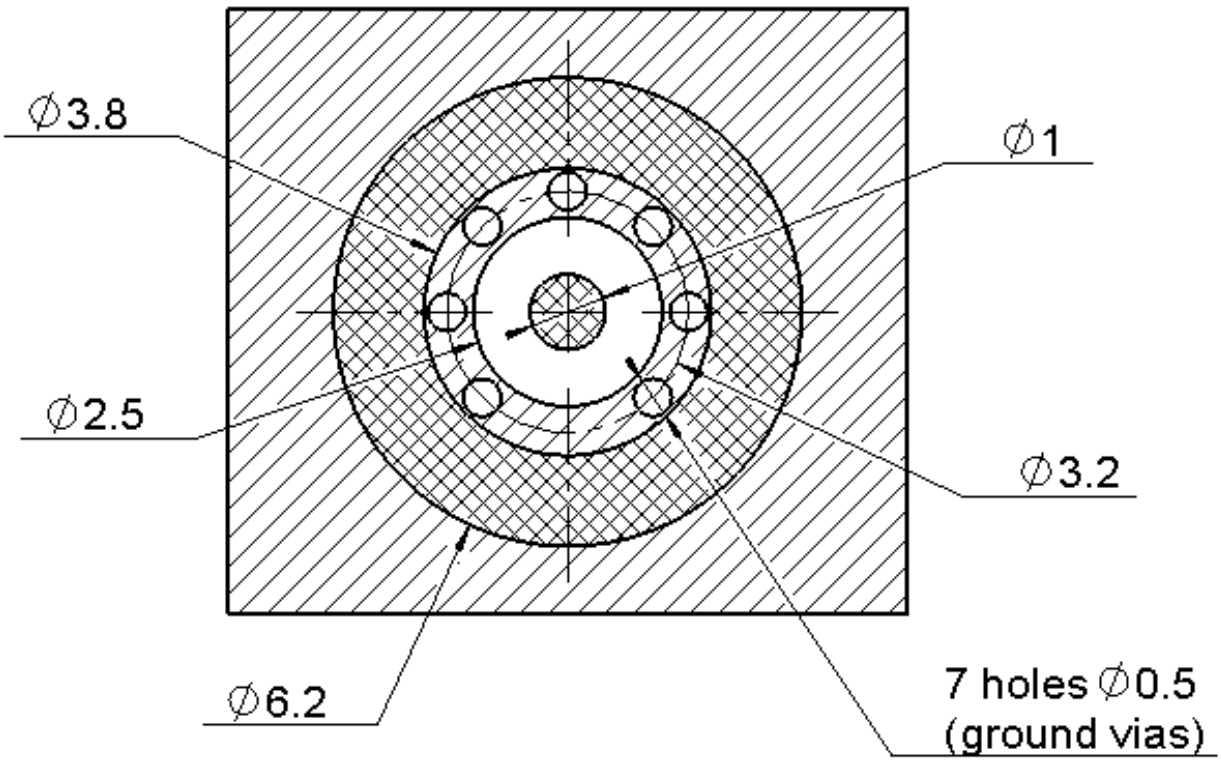
RT DUROID 6002 (30 mils) PAD (RADIALL RECOMMANDATION)



Land for solder past

Ground + varnish

-The landing pad for center contact should be linked to the stripline using a filled via.
-Upper and lower ground planes should be linked using vias.

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SOLDER PROCEDURE

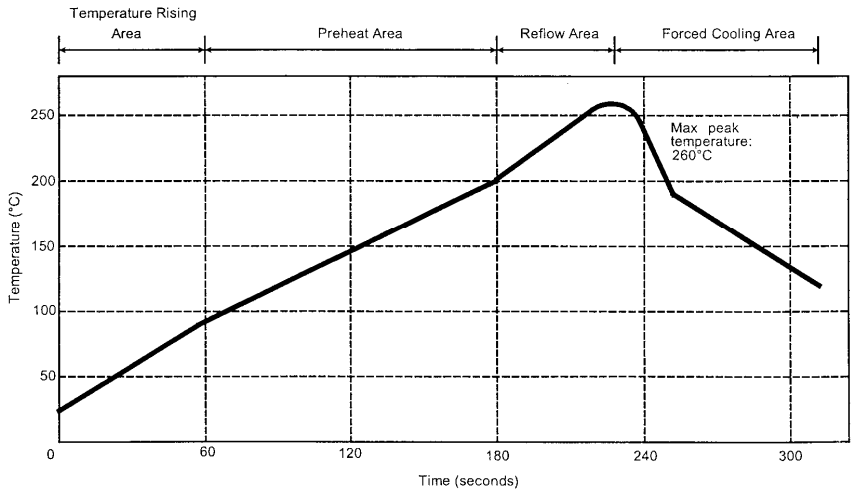
1. **Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.**
   We advise a thickness of 150 µm (5.850 microinch). Verify that the edges of the zone are clean.

2. **Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.**

3. **This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.**

4. **The cleaning of printed circuit boards is not obliged .**

Verification of solder joints and position of the component by visual inspection.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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